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To the Honorable Commissioner of Patents and Trademerks:	Please record the attached original documents or copy thereof.
Name of conveying party(ies):	Name and address of receiving party(ies)
 Chin Chen Kuo Te-Fu Tseng 	Name: Taiwan Semiconductor Manufacturing Co., Ltd.
2. Chih-Kung Chang	Internal Address:
3. Hung-Jen Hsu	Internal Address.
4. Fu-Tien Weng Additional name(s) of conveying party(es) attached? Yes ✓ No	
	+
3. Nature of conveyance:	
Assignment Merger	No 6 (1) July Dand S
Security Agreement Change of Name	Street Address: No. 8, Li-Hsin Road 6
	Science Based Industrial Park
1	City:_Hsin-Chustate:Zip:
02/25/2004	Country: Taiwan 300-77 R.O.C.
Execution Date: U2/25/2004	Additional name(s) & address(es) attached? Yes V No
 Application number(s) or patent number(s): If this document is being filed together with a new appliance. A. Patent Application No.(s) 10/781,217 	ication, the execution date of the application is: B. Patent No.(s)
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Additional numbers at	tached? Yes No
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: William H. Murray, Esquire	7. Total fee (37 CFR 3.41)\$ 40.00
Internal Address: Duane Morris LLP	Enclosed
	Authorized to be charged to deposit account 04-1679
	8 Deposit assessmt numbers
One Liberty Place	8. Deposit account number:
Street Address: One Liberty Place	04-1679
City: Philadelphia State: PA Zip: 19103	
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Ι	to y X. aa.
Steven E. Koffs	Well C. (18/14) 07/16/04
Name of Person Signing	Signature UU Date
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Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231 2-MAR-2004 14:56

☑003/005 P.Ø8

Serial No.: 10/781,217 Filed: 02/17/2004

EXPRESS MAIL LABEL NO.: EV 394066695 US

FROM

ATTORNEY DOCKET NO. N1085-00260 [TSMC2003-0953]

ASSIGNMENT AND AGREEMENT

For value received, we, Chin Chen Kuo, Chih-Kung Chang, Hung-Jen Hsu, Fu-Tien Weng, and Te-Fu Tseng, hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to IMAGE SENSOR FABRICATION METHOD AND STRUCTURE described in an application for Letters Patent of the United States and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

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Dated: /st/of	Chin Chen Kuo
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RECORDED: 07/16/2004